



Contact:
Deborah Porchivina
Porchivina & Associates Public Relations
Phone: 415-272-0943
Email: deborah@papr.com

OIF Hosts Next Generation Interconnect Workshop *Looking Beyond 100G*

Fremont, CA – December 19, 2011 –The OIF is hosting a workshop focusing on electrical and optical interconnects that will be needed for the next generation communication and computing systems. The January 16, 2012 workshop is designed to help the OIF gather industry input, and to identify application spaces for next generation interconnects. The workshop supports the OIF’s Physical & Link Layer (PLL) Working Group’s *“Next Generation Interconnect Framework”* project which will provide an overall picture of the application spaces, will identify technological challenges, and will highlight opportunities where the industry could benefit from future work by the OIF.

The workshop will investigate requirements for next generation interconnects for a wide range of application spaces: interconnects within a multichip module, Chip-to-Chip communication across a printed circuit board assembly (PCBA), Intra-rack / Backplanes and Rack-to–Rack (Within a Data Center / Campus Wide).

“We are excited to be able offer the workshop on next generation interconnects,” said Rod Smith, of TE Connectivity and the OIF MA&E Committee Chair-PLL. “The intent of the workshop is to start reviewing what is beyond 100G, to look at the application spaces and identify those areas the industry should investigate for interoperability.”

Workshop Agenda and Speakers:

Session 1 – Need for Next Generation Interconnects

The need for more bandwidth and data center overview

Session 2 - Next Generation Chip to Chip and Backplane Interconnects

Chip to chip and backplane applications and channels, and future backplane solutions

Session 3 - Next Generation Intra and Inter Rack Interconnects

Data center requirements, intra and inter rack requirements and channels, and future intra and inter rack electrical solutions

Session 4 - Next Generation Data Center, Campus and Central Office Interconnects

Central office requirements and channels and future Central Office solutions

Speakers include: Robert Brunner, Ericsson; Boris Golubovic, TE Connectivity; Scott Kipp, Brocade; Gary Nicholl, Cisco Systems; Tom Marrapode, Molex; Andy Moorwood, Infinera; Katharine Schmidtke, Finisar; Mike Tan, Hewlett Packard; Brian Welch, Luxtera.

The workshop will be held on Monday, January 16, 2012 from 8:00am-5:00pm at The Cypress Hotel in Cupertino, CA. The workshop is open to both OIF members and non-members. Fee for OIF members is \$100. Fee for non-members is \$125 (includes continental breakfast and lunch). For more details and registration, click [HERE](#)

http://www.oiforum.com/public/OIF_NextGen_Workshop_011612.html .

About the OIF

Launched in 1998, the OIF is the first industry group to unite representatives from data and optical networking disciplines, including many of the world's leading carriers, component manufacturers and system vendors. The OIF promotes the development and deployment of interoperable networking solutions and services through the creation of Implementation Agreements (IAs) for optical, interconnect, network processing, component and networking systems technologies. The OIF actively supports and extends the work of standards bodies and industry forums with the goal of promoting worldwide compatibility of optical internetworking products. Information on the OIF can be found at <http://www.oiforum.com>.